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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Domke, W. D., et al., "Pattern Collapse in High Aspect Ratio DUV and 193nm Resists," Proc. SPIE-Int. Soc. Opt. Eng. 3999, 313-321, 2000.

Cheung, C., et al., "A Study of a Single Closed Contact for 0.18 Micron Photolithography Process," Proc. SPIE-Int. Soc. Opt. Eng. 3998, 738-741, 2000.

S. Hien, et al., "Collapse behavior of single layer 193 and 157 nm resists: Use of surfactants in the rinse to realize the sub 130 nm nodes," Infineon Technologies, International SEMATECH, Center for Nano Technology, University of Wisconsin.

T. Tanaka, et al., "Mechanism of Resist Pattern Collapse During Development Process," Jpn. J. Appl. Phys. Vol. 32 (1993), pp. 6059-6064, Part 1, No. 12B.

EXAMINER DATE CONSIDERED 9/5/2005

EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this f rm with next communication to applicant.

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